

NON-CONTACT TYPE IC CARD AND PROCESS FOR
MANUFACTURING SAME

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ABSTRACT OF THE DISCLOSURE

10 A non-contact type IC card includes an insulating
film having first and second surfaces. A plane coil is
arranged on the first surface of the film. A
semiconductor element is arranged on the first surface of
the film. The film has through holes which expose
15 terminals of the plane coil and electrode terminals of
the semiconductor element to the second surface of the
film. A wiring pattern consisting of conductive paste is
filled in the through holes and extends therebetween
20 along the second surface of the film so that the
terminals of the plane coil are electrically connected to
the electrode terminals of the semiconductor element by
means of the wiring pattern.

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